



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLS810B1LD V50	Issued	16. April 2021
MA#	MA005420574		
Package	PG-TSON-10-2	Weight*	31.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	3.14	3.14	31412	31412
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8368	
	non noble metal	copper	7440-50-8	10.773	33.98	34.87	339767	348658
wire	non noble metal	copper	7440-50-8	0.022	0.07	0.07	698	698
encapsulation	organic material	carbon black	1333-86-4	0.038	0.12		1185	
	plastics	epoxy resin	-	1.935	6.10		61035	
	inorganic material	silicondioxide	60676-86-0	16.815	53.04	59.26	530349	592569
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11673	11673
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2027	2027
glue	plastics	epoxy resin	-	0.103	0.32		3241	
	noble metal	silver	7440-22-4	0.308	0.97	1.29	9722	12963
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com